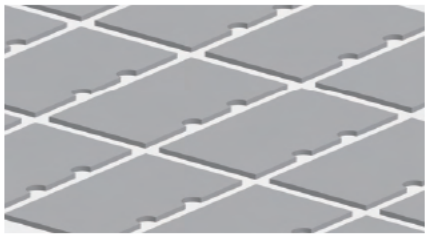
THER BS89s-5-25

Patron
Passive Elektronic

Exeptionally Soft Thermal Conductive Gel Pad



BS89s is an ultra-soft thermally conductive gel pad with a thermal conductivity of 5.0 W/m*K. BS89-s offers excellent compression under minimal force with high recovery characteristics. This product can be supplied as standard sheets, custom die-cuts or custom molded parts.

FEATURES

/ Thermal conductivity: 5.0 W/m*K / High compression rate
/ Low thermal impedance
/ High recovery
/ Available in a range of thicknesses

TYPICAL APPLICATION

/ Between CPU and heat sink
/ Between a component and heat sink
/ Notebook computers
/ Power supplies
/ High speed mass storage drives /

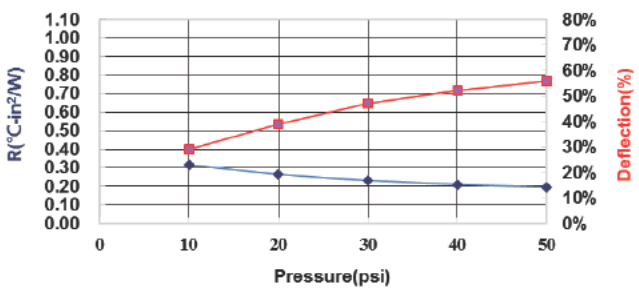
SPECIFICATIONS

/ Roll form / Sheet form
/ Die-cut parts

TYPICAL PROPERTIES

PROPERTY	BS89-s	TEST METHOD	UNIT
Color	Gray	Visual	-
Surface tack 2-side/1-side	2	-	-
Thickness	Customized	ASTM D374	mm
Density	3.0	ASTM D792	g/cm³
Hardness	25	ASTM D2240	Shore OO
Application temperature	-60~180	-	°C
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	29	ASTM D5470 modify	%
Deflection @20 psi	39	ASTM D5470 modify	%
Deflection @30 psi	47	ASTM D5470 modify	%
Deflection @40 psi	52	ASTM D5470 modify	%
Deflection @50 psi	56	ASTM D5470 modify	%
ELECTRICAL			
Dielectric breakdown	12	ASTM D149	KV/mm
Surface resistivity	$>10^{11}$	ASTM D257	Ohm
Volume resistivity	$>10^{10}$	ASTM D257	Ohm-m
THERMAL			
Thermal Conductivity	5.0	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.318	ASTM D5470	°C-in²/ W
Thermal impedance@20 psi	0.266	ASTM D5470	°C-in²/ W
Thermal impedance@30 psi	0.233	ASTM D5470	°C-in²/ W
Thermal impedance@40 psi	0.211	ASTM D5470	°C-in²/ W
Thermal impedance@50 psi	0.194	ASTM D5470	°C-in²/ W

Thermal Impedance vs. Pressure vs. Deflection



HOW TO ORDER

Patron THER **BS89s-5-25** XXX-YYY-ZZmm XXX = width in mm
YYY = depth in mm
ZZ = thickness in mm
https://www.patron-components.com/